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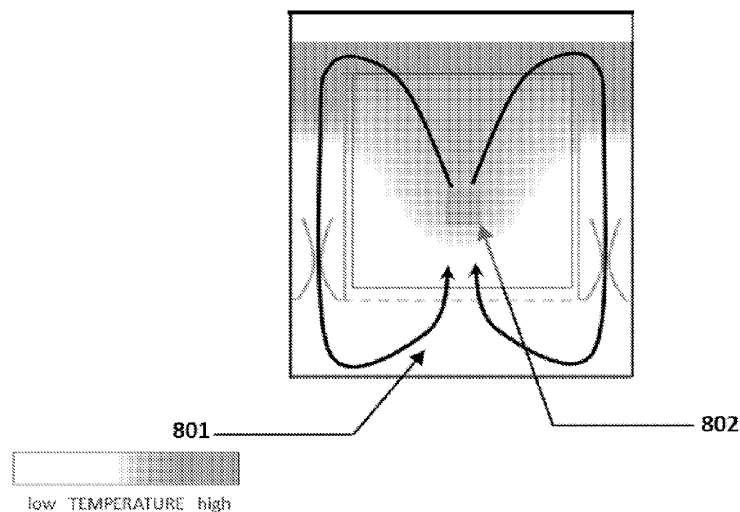


FIG. 8

(57) **Abstract:** The present disclosure provides systems and method for cooling a heat source. The system may include a container comprising a container wall and a heat source, a baffle disposed between the heat source and the container wall, and one or more of a heat exchanger or recirculation loop. The heat exchanger may be a liquid-liquid heat exchanger configured to remove heat from a liquid contacting the heat source. The recirculation loop may be configured to flow a liquid contacting the heat source to cool the heat source. Methods may use the systems described herein to cool a heat source.

[Continued on next page]

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